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WHAT IS CLAIMED IS:

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1. A method of manufacturing a semiconductor device substrate, said method comprising the steps of:

arranging on a base a temporary fixing member for temporarily fixing an electronic component;

10 temporarily fixing the electronic component on the base by using the temporary fixing member;

forming a substrate body on the base and the electronic component;

15 removing at least a portion of the base which portion corresponds to the electronic component, thereby exposing the temporary fixing member; and

removing the temporary fixing member, thereby enabling the electronic component to make an external connection.

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2. The method as claimed in claim 1, wherein the
25 temporary fixing member is made of a metal.

30 3. The method as claimed in claim 2, wherein the metal is a low-melting metal.

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4. The method as claimed in claim 1, wherein the temporary fixing member is a sheet member configured to be
5 able to bond the electronic component to the base.

10 5. The method as claimed in claim 4, wherein the sheet member is a thermo peeling tape.

15 6. The method as claimed in claim 4, wherein the sheet member is a water-soluble sheet.

20 7. The method as claimed in claim 4, wherein the sheet member is a UV tape.

25 8. The method as claimed in claim 1, wherein the temporary fixing member is a liquid adhesive.

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9. The method as claimed in claim 1, wherein the step of removing at least the portion of the base removes the entire base.

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10. A semiconductor device substrate,
comprising:

10 a base having an opening formed therein;
 an electronic component; and
 a substrate body arranged on said base and
 holding said electronic component,
 wherein the opening of the base is formed at a
15 portion corresponding to the electronic component, and
 wherein the electronic component includes an
 electrode made of a single conductive material exposed at
 the opening.

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11. The semiconductor device substrate as
claimed in claim 10, wherein the electrode of said
25 electronic component projects through said substrate body
and is connectable to an externally provided semiconductor
element.

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12. The semiconductor device substrate as
claimed in claim 10, wherein the electrode of said

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electronic component projects from a surface of said electronic component facing the opening and is connectable to an externally provided semiconductor element.

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13. The semiconductor device substrate as claimed in claim 10, wherein the substrate body has a cavity therein adjacent to the opening to which the electrode is exposed.

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14. A semiconductor device, comprising:
a semiconductor device substrate including:
a base having an opening formed therein;
an electronic component; and
a substrate body arranged on said base and holding said electronic component,
wherein the opening of the base is formed at a portion corresponding to the electronic component, and
wherein the electronic component includes an electrode made of a single conductive material; and
a semiconductor element mounted on said semiconductor device substrate and electrically connected to the electrode of said electronic component.

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15. The semiconductor device as claimed in claim 14, wherein the electrode of said electronic component projects through said substrate body.

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16. The semiconductor device as claimed in claim 14, wherein the electrode of said electronic component projects from a surface of said electronic component that faces the opening.

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17. The semiconductor device as claimed in claim 14, wherein the substrate body has a cavity therein adjacent to the opening.

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18. A semiconductor device substrate, comprising:

25 a base having an opening formed therein;
 an electronic component; and
 a substrate body arranged on said base and holding said electronic component,
 wherein the opening of the base is formed at a
30 portion corresponding to the electronic component,
 wherein the electronic component includes an electrode exposed to the opening, and
 wherein the substrate body has a cavity therein

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adjacent to the opening to which the electrode is exposed.

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19. The semiconductor device substrate as claimed in claim 18, wherein the electrode projects into the cavity.

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20. The semiconductor device substrate as claimed in claim 18, wherein a top of the electrode is substantially uniform with a surface of the substrate body that faces the opening of the base.

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21. A semiconductor device, comprising:
a semiconductor device substrate including:
a base having an opening formed therein;
an electronic component; and
25 a substrate body arranged on said base and holding said electronic component,
wherein the opening of the base is formed at a portion corresponding to the electronic component,
wherein the electronic component includes
30 an electrode, and
wherein the substrate body has a cavity therein adjacent to the opening; and
a semiconductor element mounted on said

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semiconductor device substrate and electrically connected to the electrode of said electronic component.

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22. The semiconductor device as claimed in claim 21, wherein the electrode projects into the cavity.

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23. The semiconductor device as claimed in claim 21, wherein a top of the electrode is substantially uniform with a surface of the substrate body that faces the opening of the base.

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